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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	RL78
Core Size	16-Bit
Speed	32MHz
Connectivity	CSI, I²C, IrDA, LINbus, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	58
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	5.5K × 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 17x10b; D/A 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LFQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f11bleafb-30

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

- Note 1. Total current flowing into VDD and EVDD0, including the input leakage current flowing when the level of the input pin is fixed to VDD, EVDD0 or Vss, EVss0. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.
- Note 2. When high-speed on-chip oscillator and subsystem clock are stopped.
- **Note 3.** When high-speed system clock and subsystem clock are stopped.
- **Note 4.** When high-speed on-chip oscillator and high-speed system clock are stopped. When AMPHS1 = 1 (Ultra-low power consumption oscillation). However, not including the current flowing into the RTC, 12-bit interval timer, and watchdog timer.
- **Note 5.** Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS (high-speed main) mode:	2.7 V \leq VDD \leq 5.5 V@1 MHz to 32 MHz
	2.4 V \leq VDD \leq 5.5 V@1 MHz to 16 MHz
LS (low-speed main) mode:	1.8 V \leq VDD \leq 5.5 V@1 MHz to 8 MHz
LV (low-voltage main) mode:	1.6 V \leq VDD \leq 5.5 V@1 MHz to 4 MHz

- Remark 1. fmx: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)
- Remark 2. fHoco: High-speed on-chip oscillator clock frequency (64 MHz max.)
- **Remark 3.** fil: High-speed on-chip oscillator clock frequency (32 MHz max.)
- **Remark 4.** fsub: Subsystem clock frequency (XT1 clock oscillation frequency)
- Remark 5. Except subsystem clock operation, temperature condition of the TYP. value is TA = 25°C



Parameter	Symbol			Conditions	MIN.	TYP.	MAX.	Unit	
Supply current	IDD2	HALT mode	HS (high-speed main)	fносо = 64 MHz,		0.8	3.09	mA	
Note 1 No	Note 2		mode Note 7	fiH = 32 MHz Note 4	VDD = 3.0 V		0.8	3.09	1
				fносо = 32 MHz,	VDD = 5.0 V		0.54	2.4	1
				fiH = 32 MHz Note 4	VDD = 3.0 V		0.54	2.4	1
				fносо = 48 MHz,	VDD = 5.0 V		0.62	2.4	1
				fiH = 24 MHz Note 4	VDD = 3.0 V		0.62	2.4	1
				fносо = 24 MHz,	VDD = 5.0 V		0.44	1.83	1
				fiн = 24 MHz Note 4	VDD = 3.0 V		0.44	1.83	1
				fносо = 16 MHz,	VDD = 5.0 V		0.4	1.38	
				fiH = 16 MHz Note 4	VDD = 3.0 V		0.4	1.38	
			LS (low-speed main)	fносо = 8 MHz,	VDD = 3.0 V		260	790	μA
			mode Note 7	fiH = 8 MHz Note 4	VDD = 2.0 V		260	790	
			LV (low-voltage main)	fносо = 4 MHz,	VDD = 3.0 V		420	830	μA
			mode Note 7	fiH = 4 MHz Note 4	V _{DD} = 2.0 V		420	830	
			HS (high-speed main) mode Note 7 LS (low-speed main) mode Note 7	f _{MX} = 20 MHz ^{Note 3} , VDD = 5.0 V	Square wave input		0.28	1.55	mA
					Resonator connection		0.49	1.74	
				f _{MX} = 20 MHz ^{Note 3} , V _{DD} = 3.0 V	Square wave input		0.28	1.55	
					Resonator connection		0.49	1.74	
				f _{MX} = 10 MHz ^{Note 3} , V _{DD} = 5.0 V	Square wave input		0.19	0.86	
					Resonator connection		0.3	0.93	
				f _{MX} = 10 MHz ^{Note 3} , V _{DD} = 3.0 V	Square wave input		0.19	0.86	
					Resonator connection		0.3	0.93	
				f _{MX} = 8 MHz ^{Note 3} , V _{DD} = 3.0 V	Square wave input		95	640	μA
					Resonator connection		145	680	
				f _{MX} = 8 MHz ^{Note 3} ,	Square wave input		95	640	
				VDD = 2.0 V	Resonator connection		145	680	
			Subsystem clock	fs∪в = 32.768 kHz ^{Note 5} ,	Square wave input		0.25	0.57	μA
			operation	TA = -40°C	Resonator connection		0.44	0.76	
				fsue = 32.768 kHz ^{Note 5} ,	Square wave input		0.3	0.57	
				TA = 25°C	Resonator connection		0.49	0.76	
				fsue = 32.768 kHz ^{Note 5} ,	Square wave input		0.36	1.17	
				TA = 50°C	Resonator connection		0.59	1.36	
				fsue = 32.768 kHz ^{Note 5} ,	Square wave input		0.49	1.97	
				T _A = 70°C	Resonator connection		0.72	2.16	
				fsue = 32.768 kHz ^{Note 5} ,	Square wave input		0.97	3.37	
				TA = 85°C	Resonator connection		1.16	3.56	
	IDD3	STOP mode	TA = -40°C				0.18	0.51	μA
	Note 6	Note 8	TA = +25°C				0.24	0.51	
			TA = +50°C				0.29	1.1	
			TA = +70°C				0.41	1.9	
			TA = +85°C				0.9	3.3	

(TA = -40 to +85°C, 1.6 V \leq EVDD0 \leq VDD \leq 5.5 V, VSS = EVSS0 = 0 V)

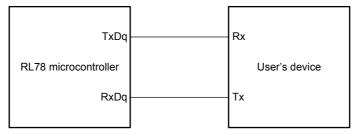
(2/2)

(Notes and Remarks are listed on the next page.)

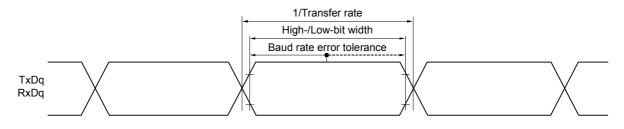
- **Note 11.** Current flowing only to the D/A converter. The supply current of the RL78 microcontrollers is the sum of IDD1 or IDD2 and IDAC when the D/A converter operates in an operation mode or the HALT mode.
- **Note 12.** Current flowing only to the comparator circuit. The supply current of the RL78 microcontrollers is the sum of IDD1, IDD2, or IDD3 and ICMP when the comparator circuit is in operation.
- Remark 1. fil: Low-speed on-chip oscillator clock frequency
- Remark 2. fsub: Subsystem clock frequency (XT1 clock oscillation frequency)
- Remark 3. fCLK: CPU/peripheral hardware clock frequency
- **Remark 4.** Temperature condition of the TYP. value is $TA = 25^{\circ}C$



UART mode connection diagram (during communication at same potential)



UART mode bit width (during communication at same potential) (reference)



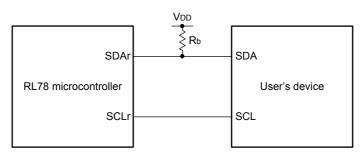
Remark 1. q: UART number (q = 0 to 2), g: PIM and POM number (g = 0, 1, 3, 5, 7)

Remark 2. fMCK: Serial array unit operation clock frequency

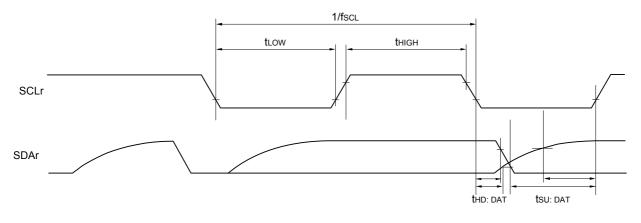
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00 to 03, 10, 11))



Simplified I²C mode connection diagram (during communication at same potential)



Simplified I²C mode serial transfer timing (during communication at same potential)



- **Remark 1.** $Rb[\Omega]$: Communication line (SDAr) pull-up resistance, Cb[F]: Communication line (SDAr, SCLr) load capacitance **Remark 2.** r: IIC number (r = 00, 01, 10, 11, 20, 21), g: PIM number (g = 0, 1, 3, 5, 7),
 - h: POM number (h = 0, 1, 3, 5, 7)
- Remark 3. fMCK: Serial array unit operation clock frequency (Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number (m = 0, 1), n: Channel number (n = 0 to 3), mn = 00 to 03, 10, 11)



(6) Communication at different potential (1.8 V, 2.5 V, 3 V) (UART mode)

Parameter	Symbol	Conditions			-speed main) node	,	-speed main) mode		voltage main) mode	Unit
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Transfer rate		reception	$\begin{array}{l} 4.0 \; V \leq EV_{DD0} \leq 5.5 \; V, \\ 2.7 \; V \leq V_b \leq 4.0 \; V \end{array}$		f _{MCK} /6 Note 1		f _{MCK} /6 Note 1		f _{MCK} /6 Note 1	bps
			Theoretical value of the maximum transfer rate $f_{MCK} = f_{CLK} Note 4$		5.3		1.3		0.6	Mbps
			$2.7 \text{ V} \le \text{EV}_{\text{DD0}} < 4.0 \text{ V},$ $2.3 \text{ V} \le \text{V}_{\text{b}} \le 2.7 \text{ V}$		f _{MCK} /6 Note 1		f _{MCK} /6 Note 1		f _{MCK} /6 Note 1	bps
			Theoretical value of the maximum transfer rate fMCK = fCLK Note 4		5.3		1.3		0.6	Mbps
			$1.8 \text{ V} \le \text{EV}_{\text{DD0}} < 3.3 \text{ V},$ $1.6 \text{ V} \le \text{V}_{\text{b}} \le 2.0 \text{ V}$		fмск/6 Notes 1, 2, 3		fмск/6 Notes 1, 2		fмск/6 Notes 1, 2	bps
			Theoretical value of the maximum transfer rate fMCK = fCLK Note 4		5.3		1.3		0.6	Mbps

Note 1. Transfer rate in the SNOOZE mode is 4800 bps only.

However, the SNOOZE mode cannot be used when FRQSEL4 = 1.

Note 2. Use it with $EV_{DD0} \ge V_b$.

Note 3.The following conditions are required for low voltage interface when EVDD0 < VDD. $2.4 V \le EVDD0 < 2.7 V$: MAX. 2.6 Mbps $1.8 V \le EVDD0 < 2.4 V$: MAX. 1.3 Mbps

Note 4. The maximum operating frequencies of the CPU/peripheral hardware clock (fcLK) are:

HS (high-speed main) mode:	32 MHz (2.7 V \leq VDD \leq 5.5 V)
	16 MHz (2.4 V \leq VDD \leq 5.5 V)
LS (low-speed main) mode:	8 MHz (1.8 V \leq VDD \leq 5.5 V)
LV (low-voltage main) mode:	4 MHz (1.6 V \leq VDD \leq 5.5 V)

Caution Select the TTL input buffer for the RxDq pin and the N-ch open drain output (VDD tolerance (for the 48-, 32-, 24pin products)/EVDD tolerance (for the 64-, 36-pin products)) mode for the TxDq pin by using port input mode register g (PIMg) and port output mode register g (POMg). For VIH and VIL, see the DC characteristics with TTL input buffer selected.

Remark 1. Vb [V]: Communication line voltage

Remark 2. q: UART number (q = 0 to 2), g: PIM and POM number (g = 0, 1, 5, 7)

Remark 3. fMCK: Serial array unit operation clock frequency (Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00 to 03, 10, 11)

Remark 4. UART2 cannot communicate at different potential when bit 1 (PIOR01) of peripheral I/O redirection register 0 (PIOR0) is 1.



(6) Communication at different potential (1.8 V, 2.5 V, 3 V) (UART mode)

(TA = -40 to +85°C, 1.8 V \leq EVDD0 \leq VDD \leq 5.5 V, VSS = EVSS0 = 0 V)											
Parameter	Symbol	Conditions	HS (high-speed main)	LS (low-speed main)							
			mode	mode							

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Parameter	Symbol	Conditions			-speed main) mode	`	speed main) node	`	voltage main) node	Unit
					MAX.	MIN.	MAX.	MIN.	MAX.	
Transfer rate		transmission	$\begin{array}{l} 4.0 \; V \leq EV_{DD0} \leq 5.5 \; V, \\ 2.7 \; V \leq V_b \leq 4.0 \; V \end{array}$		Note 1		Note 1		Note 1	bps
			Theoretical value of the maximum transfer rate C_b = 50 pF, R_b = 1.4 kΩ, V_b = 2.7 V		2.8 Note 2		2.8 Note 2		2.8 Note 2	Mbps
	$\begin{array}{c} 2.7 \ V \leq EV_{DD0} < 4.0 \ V, \\ 2.3 \ V \leq V_b \leq 2.7 \ V \end{array}$			Note 3		Note 3		Note 3	bps	
			Theoretical value of the maximum transfer rate C_b = 50 pF, R_b = 2.7 kΩ, V_b = 2.3 V		1.2 Note 4		1.2 Note 4		1.2 Note 4	Mbps
			$\begin{array}{l} 1.8 \ V \leq EV_{DD0} < 3.3 \ V, \\ 1.6 \ V \leq V_b \leq 2.0 \ V \end{array}$		Notes 5, 6		Notes 5, 6		Notes 5, 6	bps
			Theoretical value of the maximum transfer rate C_b = 50 pF, R_b = 5.5 kΩ, V_b = 1.6 V		0.43 Note 7		0.43 Note 7		0.43 Note 7	Mbps

Note 1. The smaller maximum transfer rate derived by using fMCK/6 or the following expression is the valid maximum transfer rate. Expression for calculating the transfer rate when 4.0 V \leq EVDD0 \leq 5.5 V and 2.7 V \leq Vb \leq 4.0 V

Maximum transfer rate =
$$\frac{1}{\{-C_b \times R_b \times \ln (1 - \frac{2.2}{V_b})\} \times 3}$$
[bps]
Baud rate error (theoretical value) =
$$\frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln (1 - \frac{2.2}{V_b})\}}{(\frac{1}{\text{Transfer rate}}) \times \text{Number of transferred bits}} \times 100 [\%]$$

* This value is the theoretical value of the relative difference between the transmission and reception sides.

This value as an example is calculated when the conditions described in the "Conditions" column are met. Note 2. Refer to Note 1 above to calculate the maximum transfer rate under conditions of the customer.

The smaller maximum transfer rate derived by using fMcK/6 or the following expression is the valid maximum transfer Note 3. rate.

$$\label{eq:maximum transfer rate = 1} \begin{array}{c} 1 \\ \hline \\ \hline \\ \{ -C_b \times R_b \times ln \; (1 - \frac{2.0}{V_b} \;) \} \times 3 \end{array} \end{tabular}$$
 [bps]

Baud rate error (theoretical value) =
$$\frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{2.0}{V_b})\}}{(\frac{1}{\text{Transfer rate}}) \times \text{Number of transferred bits}}$$

* This value is the theoretical value of the relative difference between the transmission and reception sides.

Expression for calculating the transfer rate when 2.7 V \leq EVDD0 < 4.0 V and 2.3 V \leq Vb \leq 2.7 V

- Note 4. This value as an example is calculated when the conditions described in the "Conditions" column are met.
 - Refer to Note 3 above to calculate the maximum transfer rate under conditions of the customer.
- Note 5. Use it with $EVDD0 \ge Vb$.

(7) Communication at different potential (2.5 V, 3 V) (CSI mode) (master mode, SCKp... internal clock output, corresponding CSI00 only)

Parameter	Symbol	Conditions	HS (high-sp mc	-	LS (low-speed main) mode		LV (low-voltage main) mode		Unit
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	İ
SIp setup time (to SCKp↓) ^{Note 2}	tsıĸı	$\begin{array}{l} 4.0 \; V \leq EV_{DD0} \leq 5.5 \; V, \\ 2.7 \; V \leq V_b \leq 4.0 \; V, \\ C_b = 20 \; pF, \; R_b = 1.4 \; k\Omega \end{array}$	23		110		110		ns
		$\begin{array}{l} 2.7 \ V \leq EV_{DD0} < 4.0 \ V, \\ 2.3 \ V \leq V_b \leq 2.7 \ V, \\ C_b = 20 \ pF, \ R_b = 2.7 \ k\Omega \end{array}$	33		110		110		ns
SIp hold time (from SCKp↓) ^{Note 2}	tksi1	$\begin{array}{l} 4.0 \; V \leq EV_{DD0} \leq 5.5 \; V, \\ 2.7 \; V \leq V_b \leq 4.0 \; V, \\ C_b = 20 \; pF, \; R_b = 1.4 \; k\Omega \end{array}$	10		10		10		ns
		$\begin{array}{l} 2.7 \ V \leq EV_{DD0} < 4.0 \ V, \\ 2.3 \ V \leq V_b \leq 2.7 \ V, \\ C_b = 20 \ pF, \ R_b = 2.7 \ k\Omega \end{array}$	10		10		10		ns
Delay time from SCKp↑ to SOp output ^{Note 2}	tkso1	$\begin{array}{l} 4.0 \; V \leq EV_{DD0} \leq 5.5 \; V, \\ 2.7 \; V \leq V_b \leq 4.0 \; V, \\ C_b = 20 \; pF, \; R_b = 1.4 \; k\Omega \end{array}$		10		10		10	ns
		$\begin{array}{l} 2.7 \ V \leq EV_{DD0} < 4.0 \ V, \\ 2.3 \ V \leq V_b \leq 2.7 \ V, \\ C_b = 20 \ pF, \ R_b = 2.7 \ k\Omega \end{array}$		10		10		10	ns

(TA = -40 to +85°C, 2.7 V \leq EVDD0 \leq VDD \leq 5.5 V, VSS = EVSS0 = 0 V)

(2/2)

Note 1. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.

Note 2. When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

Caution Select the TTL input buffer for the SIp pin and the N-ch open drain output (VDD tolerance (for the 48-, 32-, 24-pin products)/EVDD tolerance (for the 64-, 36-pin products)) mode for the SOp pin and SCKp pin by using port input mode register g (PIMg) and port output mode register g (POMg). For VIH and VIL, see the DC characteristics with TTL input buffer selected.

Remark 1. Rb[Ω]: Communication line (SCKp, SOp) pull-up resistance, Cb[F]: Communication line (SCKp, SOp) load capacitance, Vb[V]: Communication line voltage

Remark 2. p: CSI number (p = 00), m: Unit number (m = 0), n: Channel number (n = 0), g: PIM and POM number (g = 3, 5)

Remark 3. fmck: Serial array unit operation clock frequency (Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number

Remark 4. This value is valid only when CSI00's peripheral I/O redirect function is not used.

(mn = 00))



2.5.2 Serial interface IICA

(1) I²C standard mode

(TA = -40 to +85°C, 1.6 V \leq EVDD0 $\,\leq$ VDD \leq 5.5 V, Vss = EVsso = 0 V)

Parameter	Symbol	Conditions			peed main) ode	LS (low-sp mo	beed main) bde	•	ltage main) ode	Unit
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
SCLA0 clock	fscL	Standard mode:	$2.7~V \leq EV_{\text{DD0}} \leq 5.5~V$	0	100	0	100	0	100	kHz
frequency		fc∟k ≥ 1 MHz	$1.8~V \le EV_{\text{DD0}} \le 5.5~V$	0	100	0	100	0	100	kHz
			$1.7 \text{ V} \leq EV_{\text{DD0}} \leq 5.5 \text{ V}$	0	100	0	100	0	100	kHz
			$1.6~V \le EV_{\text{DD0}} \le 5.5~V$	-	_	0	100	0	100	kHz
Setup time of	tsu: sta	$2.7 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 3$	5.5 V	4.7		4.7		4.7		μs
restart condition		$1.8 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 8$	$1.8 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5 \text{ V}$			4.7		4.7		μs
		$1.7 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5 \text{ V}$		4.7		4.7		4.7		μs
		$1.6~V \leq EV_{DD0} \leq 5.5~V$		—		4.7		4.7		μs
Hold time Note 1	thd: STA	$2.7 V \le EV_{DD0} \le 3$	5.5 V	4.0		4.0		4.0		μs
		$1.8 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5 \text{ V}$		4.0		4.0		4.0		μs
		$1.7 \text{ V} \le \text{EV}_{\text{DD0}} \le 5.5 \text{ V}$		4.0		4.0		4.0		μs
		$1.6 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5 \text{ V}$		-	_	4.0		4.0		μs
Hold time when	tLOW	$2.7 \text{ V} \le \text{EV}_{\text{DD0}} \le 5.5 \text{ V}$		4.7		4.7		4.7		μs
SCLA0 = "L"		$1.8 \text{ V} \le \text{EV}_{\text{DD0}} \le 8$	5.5 V	4.7		4.7		4.7		μs
		$1.7~V \leq EV_{DD0} \leq 5.5~V$		4.7		4.7		4.7		μs
		$1.6 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 8$	$1.6 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5 \text{ V}$		_	4.7		4.7		μs
Hold time when	tнigн	$2.7 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 8$	5.5 V	4.0		4.0		4.0		μs
SCLA0 = "H"		$1.8 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 8$	5.5 V	4.0		4.0		4.0		μs
		$1.7 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 8$	5.5 V	4.0		4.0		4.0		μs
		$1.6 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 8$	5.5 V	-	_	4.0		4.0		μs

 $(\ensuremath{\textit{Notes}}, \ensuremath{\textit{Caution}}, \ensuremath{\text{and}} \ensuremath{\textit{Remark}}$ are listed on the next page.)



(4) When reference voltage (+) = Internal reference voltage (ADREFP1 = 1, ADREFP0 = 0), reference voltage (-) = AVREFM/ANI1 (ADREFM = 1), target pin: ANI0, ANI2 to ANI7, ANI16 to ANI24

(TA = -40 to +85°C, 2.4 V \leq VDD \leq 5.5 V, 1.6 V \leq EVDD0 \leq VDD, VSS = EVSS0 = 0 V, Reference voltage (+) = VBGR ^{Note 3}, Reference voltage (-) = AVREFM = 0 V ^{Note 4}, HS (high-speed main) mode)

Parameter	Symbol	Co	MIN.	TYP.	MAX.	Unit	
Resolution	RES				8		bit
Conversion time	tCONV	8-bit resolution	$2.4~\text{V} \leq \text{V}\text{DD} \leq 5.5~\text{V}$	17		39	μs
Zero-scale error Notes 1, 2	Ezs	8-bit resolution	$2.4~V \leq V_{DD} \leq 5.5~V$			±0.60	% FSR
Integral linearity error Note 1	ILE	8-bit resolution	$2.4~V \leq V_{DD} \leq 5.5~V$			±2.0	LSB
Differential linearity error Note 1	DLE	8-bit resolution	$2.4~V \leq V_{DD} \leq 5.5~V$			±1.0	LSB
Analog input voltage	Vain			0		VBGR Note 3	V

Note 1. Excludes quantization error (±1/2 LSB).

Note 2. This value is indicated as a ratio (% FSR) to the full-scale value.

Note 3. Refer to 2.6.2 Temperature sensor characteristics/internal reference voltage characteristic.

Note 4. When reference voltage (-) = Vss, the MAX. values are as follows.

Zero-scale error:Add ±0.35%FSR to the MAX. value when reference voltage (-) = AVREFM.Integral linearity error:Add ±0.5 LSB to the MAX. value when reference voltage (-) = AVREFM.Differential linearity error:Add ±0.2 LSB to the MAX. value when reference voltage (-) = AVREFM.



(2) Interrupt & Reset Mode

Parameter	Symbol		Con	ditions	MIN.	TYP.	MAX.	Unit
Voltage detection	VLVDA0	VPOC2,	, VPOC1, VPOC0 = 0, 0, 0, f	alling reset voltage	1.60	1.63	1.66	V
threshold	VLVDA1		LVIS1, LVIS0 = 1, 0	Rising release reset voltage	1.74	1.77	1.81	V
				Falling interrupt voltage	1.70	1.73	1.77	V
	VLVDA2	VLVDA2	LVIS1, LVIS0 = 0, 1	Rising release reset voltage	1.84	1.88	1.91	V
				Falling interrupt voltage	1.80	1.84	1.87	V
	VLVDA3	-	LVIS1, LVIS0 = 0, 0	Rising release reset voltage	2.86	2.92	2.97	V
				Falling interrupt voltage	2.80	2.86	2.91	V
	VLVDB0	VPOC2,	, VPOC1, VPOC0 = 0, 0, 1, f	alling reset voltage	1.80	1.84	1.87	V
	VLVDB1	-	LVIS1, LVIS0 = 1, 0	Rising release reset voltage	1.94	1.98	2.02	V
				Falling interrupt voltage	1.90	1.94	1.98	V
	VLVDB2	-	LVIS1, LVIS0 = 0, 1	Rising release reset voltage	2.05	2.09	2.13	V
				Falling interrupt voltage	2.00	2.04	2.08	V
	VLVDB3	VLVDB3	LVIS1, LVIS0 = 0, 0	Rising release reset voltage	3.07	3.13	3.19	V
				Falling interrupt voltage	3.00	3.06	3.12	V
	VLVDC0	VPOC2, VPOC1, VPOC0 = 0, 1, 0, falling reset voltage			2.40	2.45	2.50	V
	VLVDC1	VLVDC1	LVIS1, LVIS0 = 1, 0	Rising release reset voltage	2.56	2.61	2.66	V
				Falling interrupt voltage	2.50	2.55	2.60	V
	VLVDC2	-	LVIS1, LVIS0 = 0, 1	Rising release reset voltage	2.66	2.71	2.76	V
				Falling interrupt voltage	2.60	2.65	2.70	V
	VLVDC3	-	LVIS1, LVIS0 = 0, 0	Rising release reset voltage	3.68	3.75	3.82	V
				Falling interrupt voltage	3.60	3.67	3.74	V
	VLVDD0	VPOC2,	, VPOC1, VPOC0 = 0, 1, 1, f	alling reset voltage	2.70	2.75	2.81	V
	VLVDD1	1	LVIS1, LVIS0 = 1, 0	Rising release reset voltage	2.86	2.92	2.97	V
				Falling interrupt voltage	2.80	2.86	2.91	V
	VLVDD2	1	LVIS1, LVIS0 = 0, 1	Rising release reset voltage	2.96	3.02	3.08	V
				Falling interrupt voltage	2.90	2.96	3.02	V
	VLVDD3	1	LVIS1, LVIS0 = 0, 0	Rising release reset voltage	3.98	4.06	4.14	V
				Falling interrupt voltage	3.90	3.98	4.06	V

2.6.8 Power supply voltage rising slope characteristics

(TA = -40 to +85°C, Vss = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Power supply voltage rising slope	SVDD				54	V/ms

Caution Make sure to keep the internal reset state by the LVD circuit or an external reset until VDD reaches the operating voltage range shown in 2.4 AC Characteristics.



(1/2)

3.1 Absolute Maximum Ratings

Absolute Maximum Ratings

Parameter	Symbols	Conditions	Ratings	Unit
Supply voltage	Vdd		-0.5 to +6.5	V
	EVDD0		-0.5 to +6.5	V
REGC pin input voltage	VIREGC	REGC	-0.3 to +2.8	V
			and -0.3 to V _{DD} +0.3 ^{Note 1}	
Input voltage	VI1	P00 to P06, P10 to P17, P30, P31,	-0.3 to EVDD0 +0.3	V
		P40 to P43, P50 to P55, P70 to P77, P120, P140, P141, P146, P147	and -0.3 to V _{DD} +0.3 Note 2	
	Vı2	P60 to P63 (N-ch open-drain)	-0.3 to +6.5	V
	VI3	P20 to P27, P121 to P124, P137, EXCLK, EXCLKS, RESET	-0.3 to V _{DD} +0.3 Note 2	V
Output voltage	Vo1	P00 to P06, P10 to P17, P30, P31, P40 to P43, P50 to P55, P60 to P63, P70 to P77, P120, P130, P140, P141, P146, P147	-0.3 to EVDD0 +0.3 and -0.3 to VDD +0.3 Note 2	V
	V02	P20 to P27	-0.3 to VDD +0.3 Note 2	V
Analog input voltage	VAI1	ANI16 to ANI24	-0.3 to EVDD0 +0.3 and -0.3 to AVREF(+) +0.3 Notes 2, 3	V
	VAI2	ANI0 to ANI7	-0.3 to VDD +0.3 and -0.3 to AVREF(+) +0.3 Notes 2, 3	V

Note 1. Connect the REGC pin to Vss via a capacitor (0.47 to 1 μF). This value regulates the absolute maximum rating of the REGC pin. Do not use this pin with voltage applied to it.

Note 2. Must be 6.5 V or lower.

Note 3. Do not exceed AVREF (+) + 0.3 V in case of A/D conversion target pin.

- Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.
- Remark 1. Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.
- Remark 2. AVREF (+): + side reference voltage of the A/D converter.
- Remark 3. Vss: Reference voltage



Items	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Output current, low ^{Note 1}	IOL1	Per pin for P00 to P06, P10 to P17, P30, P31, P40 to P43, P50 to P55, P70 to P77,P120, P130, P140, P141, P146, P147				8.5 Note 2	mA
		Per pin for P60 to P63				15.0 Note 2	mA
		Total of P00 to P04, P40 to P43, P120, P130, P140, P141 (When duty \leq 70% ^{Note 3})	$4.0~V \leq EV_{DD0} \leq 5.5~V$			40.0	mA
			$2.7 \text{ V} \le \text{EV}_{\text{DD0}} < 4.0 \text{ V}$			15.0	mA
			$2.4 \text{ V} \le \text{EV}_{\text{DD0}} < 1.8 \text{ V}$			9.0	mA
		Total of P05, P06, P10 to P17,	$4.0~V \leq EV_{DD0} \leq 5.5~V$			40.0	mA
	P30, P31, P50 to P55, P60 to	$2.7 \text{ V} \le \text{EV}_{\text{DD0}} < 4.0 \text{ V}$			35.0	mA	
		P63, P70 to P77, P146, P147 (When duty ≤ 70% ^{Note 3})	$2.4 \text{ V} \leq \text{EV}_{\text{DD0}} < 1.8 \text{ V}$			20.0	mA
		Total of all pins (When duty ≤ 70% ^{Note 3})				80.0	mA
	Iol2 F	Per pin for P20 to P27				0.4 Note 2	mA
		Total of all pins (When duty \leq 70% ^{Note 3})	$2.4~V \leq V \text{DD} \leq 5.5~V$			5.0	mA

 $40.45 + 40.5^{\circ}C$ 2.4.17 = 51/555 = 51/575 = 51/575 = 51/575 = 0.10

(0/E)

Note 1. Value of current at which the device operation is guaranteed even if the current flows from an output pin to the EVsso and Vss pins.

Note 2. Do not exceed the total current value.

Note 3. Specification under conditions where the duty factor \leq 70%. The output current value that has changed to the duty factor > 70% the duty ratio can be calculated with the following expression (when changing the duty factor from 70% to n%).

• Total output current of pins = (IoL × 0.7)/(n × 0.01)

<Example> Where n = 80% and IoL = 10.0 mA

Total output current of pins = $(10.0 \times 0.7)/(80 \times 0.01) \approx 8.7$ mA

However, the current that is allowed to flow into one pin does not vary depending on the duty factor.

A current higher than the absolute maximum rating must not flow into one pin.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.



Parameter	Symbol	Condit	ions	MIN.	TYP.	MAX.	Unit
Low-speed on-chip oscilla- tor operating current	I _{FIL} Note 1				0.2		μA
RTC operating current	IRTC Notes 1, 2, 3				0.02		μA
12-bit interval timer operat- ing current	IIT Notes 1, 2, 4				0.02		μA
Watchdog timer operating current	IWDT Notes 1, 2, 5	fı∟ = 15 kHz			0.22		μA
A/D converter operating cur- rent	IADC Notes 1, 6	When conversion at maximum speed	Normal mode, AV _{REFP} = V _{DD} = 5.0 V		1.3	1.7	mA
			Low voltage mode, AV _{REFP} = V _{DD} = 3.0 V		0.5	0.7	mA
A/D converter reference voltage current	IADREF Note 1				75		μΑ
Temperature sensor operat- ing current	ITMPS Note 1				75		μA
D/A converter operating cur- rent	IDAC Notes 1, 11	Per D/A converter channel				1.5	mA
PGA operating current		Operation			480	700	μΑ
Comparator operating cur- rent	I _{CMP} Notes 1, 12	Operation (per comparator chan- nel, constant current for compara-	When the internal reference voltage is not in use		50	100	μA
		tor included)	When the internal reference voltage is in use		60	110	μA
LVD operating current	ILVD Notes 1, 7				0.08		μΑ
Self-programming operat- ing current	IFSP Notes 1, 9				2.50	12.2	mA
BGO operating current	IBGO Notes 1, 8				2.50	12.2	mA
SNOOZE operating current	ISNOZ Note 1	ADC operation	The mode is performed Note 10		0.50	1.10	mA
			The A/D conversion opera- tions are performed, Low volt- age mode, AV _{REFP} = V _{DD} = 3.0 V		1.20	2.04	
		CSI/UART operation	•		0.70	1.54	
		DTC operation			3.10		

(TA = -40 to +105°C, 2.4 V \leq EVDD0 \leq VDD \leq 5.5 V	, Vss = EVsso = 0 V)
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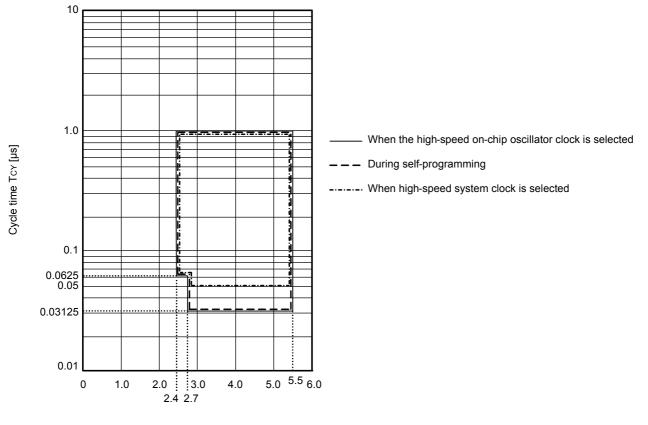
Note 1. Current flowing to VDD.

Note 2. When high speed on-chip oscillator and high-speed system clock are stopped.

- Note 3. Current flowing only to the real-time clock (RTC) (excluding the operating current of the low-speed on-chip oscillator and the XT1 oscillator). The supply current of the RL78 microcontrollers is the sum of the values of either IDD1 or IDD2, and IRTC, when the real-time clock operates in operation mode or HALT mode. When the low-speed on-chip oscillator is selected, IFIL should be added. IDD2 subsystem clock operation includes the operational current of the real-time clock.
- Note 4. Current flowing only to the 12-bit interval timer (excluding the operating current of the low-speed on-chip oscillator and the XT1 oscillator). The supply current of the RL78 microcontrollers is the sum of the values of either IDD1 or IDD2, and IIT, when the 12-bit interval timer operates in operation mode or HALT mode. When the low-speed on-chip oscillator is selected, IFIL should be added.
- Note 5. Current flowing only to the watchdog timer (including the operating current of the low-speed on-chip oscillator). The supply current of the RL78 microcontrollers is the sum of IDD1, IDD2 or IDD3 and IWDT when the watchdog timer is in operation.
- **Note 6.** Current flowing only to the A/D converter. The supply current of the RL78 microcontrollers is the sum of IDD1 or IDD2 and IADC when the A/D converter operates in an operation mode or the HALT mode.
- Note 7. Current flowing only to the LVD circuit. The supply current of the RL78 microcontrollers is the sum of IDD1, IDD2 or IDD3 and ILVD when the LVD circuit is in operation.
- **Note 8.** Current flowing during programming of the data flash.
- **Note 9.** Current flowing during self-programming.
- Note 10. For shift time to the SNOOZE mode, see 26.3.3 SNOOZE mode in the RL78/G1F User's Manual.

Minimum Instruction Execution Time during Main System Clock Operation

TCY vs VDD (HS (high-speed main) mode)

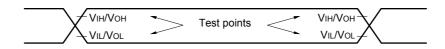


Supply voltage VDD [V]



3.5 Peripheral Functions Characteristics

AC Timing Test Points



3.5.1 Serial array unit

(1) During communication at same potential (UART mode)

$(TA = -40 \text{ to } +105^{\circ}C, 2.4 \text{ V} \le EVDD0 \le 5.5 \text{ V}, \text{ Vss} = EVss0 = 0 \text{ V})$

Parameter	Symbol	Conditions	Conditions HS (high-speed main) Mode						
			MIN.	MAX.					
Transfer rate	$2.4 \text{ V} \le \text{EV}_{\text{DD0}} \le 5.5 \text{ V}$			fмск/12 Note 2	bps				
Note 1		Theoretical value of the maximum transfer rate fMCK = fcLK Note 3		2.6	Mbps				
Note 1. Transfer rate in the SNOOZE mode is 4800 bps only.									

 However, the SNOOZE mode cannot be used when FRQSEL4 = 1.

 Note 2.
 The following conditions are required for low voltage interface when EVDD0 < VDD.</td>

 2.4 V ≤ EVDD0 < 2.7 V: MAX.1.3 Mbps</td>

 Note 3.
 The maximum operating frequencies of the CPU/peripheral hardware clock (fcLK) are:

HS (high-speed main) mode: 32 MHz (2.7 V \leq VDD \leq 5.5 V) 16 MHz (2.4 V \leq VDD \leq 5.5 V)

Caution Select the normal input buffer for the RxDq pin and the normal output mode for the TxDq pin by using port input mode register g (PIMg) and port output mode register g (POMg).



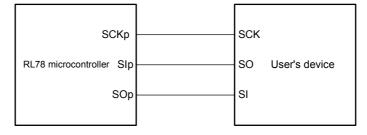
(3) During communication at same potential (CSI mode) (slave mode, SCKp... external clock input) (TA = -40 to +105°C, 2.4 V \leq EVDD0 \leq VDD \leq 5.5 V, Vss = EVss0 = 0 V)(2/2)

Parameter	Symbol	Conditions		HS (high-speed ma	HS (high-speed main) mode		
				MIN.	MAX.		
SSI00 setup time	tssik	DAPmn = 0	$2.7~\text{V} \leq \text{EV}_{\text{DD0}} \leq 5.5~\text{V}$	240		ns	
			$2.4 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5 \text{ V}$	400		ns	
		DAPmn = 1	$2.7 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5 \text{ V}$	1/fмск + 240		ns	
			$2.4 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5 \text{ V}$	1/fмск + 400		ns	
SSI00 hold time	tĸssi	DAPmn = 0	$2.7 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5 \text{ V}$	1/fмск + 240		ns	
			$2.4~\text{V} \leq \text{EV}_{\text{DD0}} \leq 5.5~\text{V}$	1/fмск + 400		ns	
		DAPmn = 1	$2.7 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5 \text{ V}$	240		ns	
			$2.4 \text{ V} \le \text{EV}_{\text{DD0}} \le 5.5 \text{ V}$	400		ns	

Caution Select the normal input buffer for the SIp pin and SCKp pin and the normal output mode for the SOp pin by using port input mode register g (PIMg) and port output mode register g (POMg).

Remark p: CSI number (p = 00), m: Unit number (m = 0), n: Channel number (n = 0), g: PIM number (g = 3, 5)

CSI mode connection diagram (during communication at same potential)

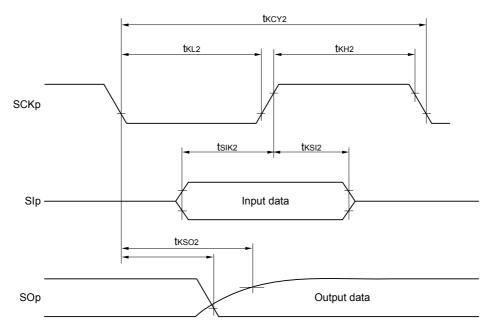


CSI mode connection diagram (during communication at same potential) (Slave Transmission of slave select input function (CSI00))

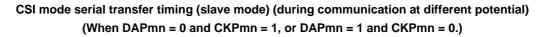
SCK00	SCK
SI00	so
RL78 microcontroller SO00	 User's device SI
<u>SSI00</u>	SSO

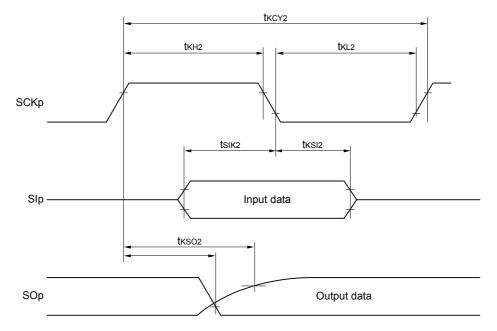
Remark 1. p: CSI number (p = 00, 01, 10, 11, 20, 21) **Remark 2.** m: Unit number, n: Channel number (mn = 00 to 03, 10, 11)





CSI mode serial transfer timing (slave mode) (during communication at different potential) (When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)





- **Remark 1.** p: CSI number (p = 00, 01, 10, 20), m: Unit number (m = 0, 1), n: Channel number (n = 0 to 3), g: PIM and POM number (g = 0, 1, 3, 5, 7)
- Remark 2. CSI01 of 48-, 64-pin products, and CSI11 and CSI21 cannot communicate at different potential. Use other CSI for communication at different potential.
 Also, communication at different potential cannot be performed during clock synchronous serial communication with the slave select function.

(4) When reference voltage (+) = Internal reference voltage (ADREFP1 = 1, ADREFP0 = 0), reference voltage (-) = AVREFM/ANI1 (ADREFM = 1), target pin: ANI0, ANI2 to ANI7, ANI16 to ANI24

(TA = -40 to +105°C, 2.4 V \leq VDD \leq 5.5 V, 2.4 V \leq EVDD0 \leq VDD, VSs = EVSs0 = 0 V, Reference voltage (+) = VBGR ^{Note 3}, Reference voltage (-) = AVREFM = 0 V ^{Note 4}, HS (high-speed main) mode)

Parameter	Symbol	Co	MIN.	TYP.	MAX.	Unit	
Resolution	RES		8			bit	
Conversion time	tconv	8-bit resolution	$2.4~\text{V} \leq \text{V}\text{DD} \leq 5.5~\text{V}$	17		39	μs
Zero-scale error Notes 1, 2	Ezs	8-bit resolution	$2.4~V \leq V \text{DD} \leq 5.5~V$			±0.60	% FSR
Integral linearity error Note 1	ILE	8-bit resolution	$2.4~V \leq V \text{DD} \leq 5.5~V$			±2.0	LSB
Differential linearity error Note 1	DLE	8-bit resolution	$2.4~V \leq V \text{DD} \leq 5.5~V$			±1.0	LSB
Analog input voltage	VAIN			0		VBGR Note 3	V

Note 1. Excludes quantization error (±1/2 LSB).

Note 2. This value is indicated as a ratio (% FSR) to the full-scale value.

Note 3. Refer to 3.6.2 Temperature sensor characteristics/internal reference voltage characteristic.

Note 4. When reference voltage (-) = Vss, the MAX. values are as follows.

Zero-scale error:Add ±0.35%FSR to the MAX. value when reference voltage (-) = AVREFM.Integral linearity error:Add ±0.5 LSB to the MAX. value when reference voltage (-) = AVREFM.Differential linearity error:Add ±0.2 LSB to the MAX. value when reference voltage (-) = AVREFM.



4.5 64-pin products

R5F11BLCAFB, R5F11BLEAFB, R5F11BLCGFB, R5F11BLEGFB

